SCLS140D - DECEMBER 1982 - REVISED AUGUST 2003

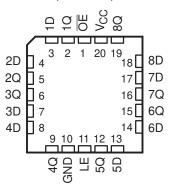
- Wide Operating Voltage Range of 2 V to 6 V
- High-Current 3-State True Outputs Can Drive Up To 15 LSTTL Loads
- Low Power Consumption, 80-μA Max I_{CC}
- Typical t_{pd} = 13 ns

SN54HC373 . . . J OR W PACKAGE SN74HC373 . . . DB, DW, N, NS, OR PW PACKAGE (TOP VIEW)

			_	
OE	d 1	\bigcup_{2}	ᅊ	V _{CC}
1Q	2	1	9	8Q
1D	[]3	1	8	8D
2D	[] 4	1	7	7D
2Q	[] 5	1	6	7Q
3Q	6	1	5	6Q
3D	[]7	1	4 [6D
4D	8 🛚	1	з[5D
4Q	9	1	2	5Q
GND	10	1	1] LE

- ±6-mA Output Drive at 5 V
- Low Input Current of 1 μA Max
- Eight High-Current Latches in a Single Package
- Full Parallel Access for Loading





description/ordering information

These 8-bit latches feature 3-state outputs designed specifically for driving highly capacitive or relatively low-impedance loads. They are particularly suitable for implementing buffer registers, I/O ports, bidirectional bus drivers, and working registers.

The eight latches of the 'HC373 devices are transparent D-type latches. While the latch-enable (LE) input is high, the Q outputs follow the data (D) inputs. When LE is taken low, the Q outputs are latched at the levels that were set up at the D inputs.

ORDERING INFORMATION

TA	PACKA	GET	ORDERABLE PART NUMBER	TOP-SIDE MARKING
	PDIP – N	Tube of 20	SN74HC373N	SN74HC373N
	COIC DW	Tube of 25	SN74HC373DW	110070
	SOIC – DW	Reel of 2000	SN74HC373DWR	HC373
4000 +- 0500	SOP - NS	Reel of 2000	SN74HC373NSR	HC373
-40°C to 85°C	SSOP – DB	Reel of 2000	SN74HC373DBR	HC373
		Tube of 70	SN74HC373PW	
	TSSOP - PW	Reel of 2000	SN74HC373PWR	HC373
		Reel of 250	SN74HC373PWT	
	CDIP – J	Tube of 20	SNJ54HC373J	SNJ54HC373J
–55°C to 125°C	CFP – W	Tube of 85	SNJ54HC373W	SNJ54HC373W
	LCCC – FK	Tube of 55	SNJ54HC373FK	SNJ54HC373FK

[†] Package drawings, standard packing quantities, thermal data, symbolization, and PCB design guidelines are available at www.ti.com/sc/package.



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processing does not necessarily include testing of all pa

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description/ordering information (continued)

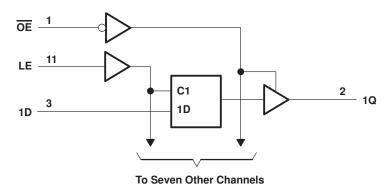
An output-enable (OE) input places the eight outputs in either a normal logic state (high or low logic levels) or the high-impedance state. In the high-impedance state, the outputs neither load nor drive the bus lines significantly. The high-impedance state and increased drive provide the capability to drive bus lines without interface or pullup components.

OE does not affect the internal operations of the latches. Old data can be retained or new data can be entered while the outputs are off.

FUNCTION TABLE (each latch)

	INPUTS		OUTPUT
OE	LE	D	Q
L	Н	Н	Н
L	Н	L	L
L	L	Χ	Q ₀
Н	X	Χ	Z

logic diagram (positive logic)



absolute maximum ratings over operating free-air temperature range (unless otherwise noted)

Supply voltage range, V _{CC}		0.5	V to 7 V
Input clamp current, I_{IK} ($V_I < 0$ or $V_I > V_{CC}$) (se	ee Note 1)		±20 mA
Output clamp current, IOK (VO < 0 or VO > VCO	c) (see Note 1)		±20 mA
Continuous output current, $I_O (V_O = 0 \text{ to } V_{CC})$	- 		±35 mA
Continuous current through V _{CC} or GND			±70 mA
Package thermal impedance, θ _{JA} (see Note 2):	: DB package		70°C/W
	DW package		58°C/W
	N package		69°C/W
	NS package		60°C/W
	PW package		83°C/W
Storage temperature range, Teta		-65°C t	to 150°C

[†] Stresses beyond those listed under "absolute maximum ratings" may cause permanent damage to the device. These are stress ratings only, and functional operation of the device at these or any other conditions beyond those indicated under "recommended operating conditions" is not implied. Exposure to absolute-maximum-rated conditions for extended periods may affect device reliability.



NOTES: 1. The input and output voltage ratings may be exceeded if the input and output current ratings are observed.

^{2.} The package thermal impedance is calculated in accordance with JESD 51-7.

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recommended operating conditions (see Note 3)

			SI	154HC37	'3	SN	174HC37	'3	LINUT	
			MIN	NOM	MAX	MIN	NOM	MAX	UNIT	
VCC	Supply voltage		2	5	6	2	5	6	V	
		V _{CC} = 2 V	1.5			1.5				
VIH	High-level input voltage	$V_{CC} = 4.5 \text{ V}$	3.15			3.15			V	
		V _{CC} = 6 V	4.2			4.2				
		V _{CC} = 2 V			0.5			0.5		
VIL	Low-level input voltage	V _{CC} = 4.5 V			1.35			1.35	V	
		V _{CC} = 6 V			1.8			1.8		
٧ı	Input voltage		0		VCC	0		VCC	V	
٧o	Output voltage		0		VCC	0		VCC	V	
		V _{CC} = 2 V			1000			1000		
Δt/Δν	Input transition rise/fall time	V _{CC} = 4.5 V			500			500	ns	
		V _{CC} = 6 V			400			400		
TA	Operating free-air temperature		-55		125	-40		85	°C	

NOTE 3: All unused inputs of the device must be held at V_{CC} or GND to ensure proper device operation. Refer to the TI application report, Implications of Slow or Floating CMOS Inputs, literature number SCBA004.

electrical characteristics over recommended operating free-air temperature range (unless otherwise noted)

			.,	Т	_A = 25°C	;	SN54H	IC373	SN74HC373		
PARAMETER	TEST CC	ONDITIONS	vcc	MIN	TYP	MAX	MIN	MAX	MIN	MAX	UNIT
			2 V	1.9	1.998		1.9		1.9		
		$I_{OH} = -20 \mu A$	4.5 V	4.4	4.499		4.4		4.4		
VOH	VI = VIH or VIL		6 V	5.9	5.999		5.9		5.9		V
		$I_{OH} = -6 \text{ mA}$	4.5 V	3.98	4.3		3.7		3.84		
		$I_{OH} = -7.8 \text{ mA}$	6 V	5.48	5.8		5.2		5.34		
			2 V		0.002	0.1		0.1		0.1	
		I _{OL} = 20 μA	4.5 V		0.001	0.1		0.1		0.1	
V _{OL}	VI = VIH or VIL		6 V		0.001	0.1		0.1		0.1	V
		I _{OL} = 6 mA	4.5 V		0.17	0.26		0.4		0.33	
		$I_{OL} = 7.8 \text{ mA}$	6 V		0.15	0.26		0.4		0.33	
lį	$V_I = V_{CC}$ or 0		6 V		±0.1	±100		±1000	:	±1000	nA
loz	$V_O = V_{CC}$ or 0	•	6 V		±0.01	±0.5		±10		±5	μΑ
ICC	$V_I = V_{CC}$ or 0,	IO = 0	6 V			8		160		80	μΑ
Ci			2 V to 6 V		3	10		10		10	pF

SN54HC373, SN74HC373 OCTAL TRANSPARENT D-TYPE LATCHES WITH 3-STATE OUTPUTS

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timing requirements over recommended operating free-air temperature range (unless otherwise noted)

		,,	T _A = 25°C		SN54HC373		SN74HC373		UNIT	
		VCC	MIN	MAX	MIN	MAX	MIN	MAX	UNII	
		2 V	80		120		100			
t _w	Pulse duration, LE high	4.5 V	16		24		20		ns	
		6 V	14		20		17			
		2 V	50		75		63			
t _{su}	Setup time, data before LE↓	4.5 V	10		15		13		ns	
		6 V	9		13		11			
		2 V	20		26		24		_	
th	Hold time, data after LE \downarrow	4.5 V	10		13		12		ns	
		6 V	10		13		12		 	

switching characteristics over recommended operating free-air temperature range, C_L = 50 pF (unless otherwise noted) (see Figure 1)

DADAMETED	FROM	то		T,	ղ = 25°C	;	SN54H	C373	SN74H	C373	
PARAMETER	(INPUT)	(OUTPUT)	VCC	MIN	TYP	MAX	MIN	MAX	MIN	MAX	UNIT
			2 V		58	150		225		190	
	D	Q	4.5 V		15	30		45		38	
			6 V		13	26		38		32	
^t pd			2 V		73	175		265		220	ns
	LE	Any Q	4.5 V		18	35		53		44	
			6 V		15	30		45		38	
			2 V		65	150		225		190	
t _{en}	ŌĒ	Any Q	4.5 V		17	30		45		38	ns
			6 V		14	26		38		32	
			2 V		50	150		225		190	
^t dis	ŌĒ	Any Q	4.5 V		15	30		45		38	ns
			6 V		13	26		38		32	
			2 V		28	60	·	90		75	
t _t		Any Q	4.5 V		8	12		18		15	ns
			6 V		6	10		15		13	

SN54HC373, SN74HC373 **OCTAL TRANSPARENT D-TYPE LATCHES** WITH 3-STATE OUTPUTS SCLS140D - DECEMBER 1982 - REVISED AUGUST 2003

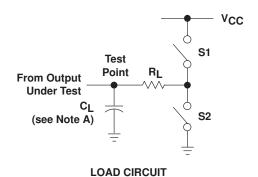
switching characteristics over recommended operating free-air temperature range, C_L = 150 pF (unless otherwise noted) (see Figure 1)

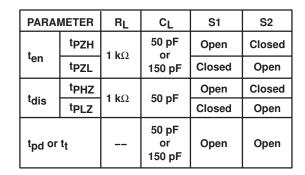
DADAMETED	FROM	то	.,	T,	Վ = 25° C	;	SN54HC373		SN74HC373		
PARAMETER	(INPUT)	(OUTPUT)	vcc	MIN	TYP	MAX	MIN	MAX	MIN	MAX	UNIT
			2 V		82	200		300		250	
	D	Q	4.5 V		22	40		60		50	
			6 V		19	34		51		43	
^t pd	LE		2 V		100	225		335		285	ns
		Any Q	4.5 V		24	45		67		57	
			6 V		20	38		57		48	
		Any Q	2 V		90	200		300		250	
^t en	ŌĒ		4.5 V		23	40		60		50	ns
			6 V		19	34		51		43	
		Any Q	2 V		45	210		315		265	
t _t			4.5 V		17	42	·	63	·	53	ns
			6 V		13	36		53		45	

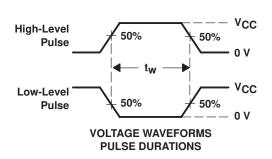
operating characteristics, $T_A = 25^{\circ}C$

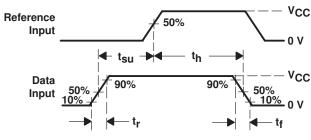
	PARAMETER	TEST CONDITIONS	TYP	UNIT
(pd Power dissipation capacitance per latch	No load	100	pF

PARAMETER MEASUREMENT INFORMATION

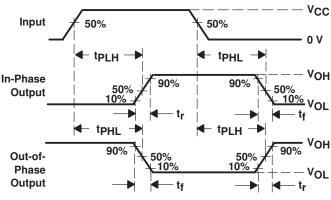


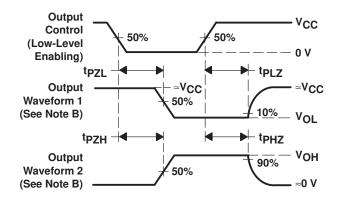






VOLTAGE WAVEFORMS
SETUP AND HOLD AND INPUT RISE AND FALL TIMES





VOLTAGE WAVEFORMS
PROPAGATION DELAY AND OUTPUT TRANSITION TIMES

VOLTAGE WAVEFORMS
ENABLE AND DISABLE TIMES FOR 3-STATE OUTPUTS

NOTES: A. C_L includes probe and test-fixture capacitance.

- B. Waveform 1 is for an output with internal conditions such that the output is low except when disabled by the output control. Waveform 2 is for an output with internal conditions such that the output is high except when disabled by the output control.
- C. Phase relationships between waveforms were chosen arbitrarily. All input pulses are supplied by generators having the following characteristics: PRR \leq 1 MHz, $Z_O = 50 \ \Omega$, $t_r = 6 \ ns$, $t_f = 6 \ ns$.
- D. The outputs are measured one at a time with one input transition per measurement.
- E. tpl 7 and tpH7 are the same as tdis.
- F. tpzL and tpzH are the same as ten.
- G. tpLH and tpHL are the same as tpd.

Figure 1. Load Circuit and Voltage Waveforms









PACKAGING INFORMATION

Orderable Device	Status ⁽¹⁾	Package Type	Package Drawing	Pins	Package Qty	Eco Plan (2)	Lead/Ball Finish	MSL Peak Temp (3)
5962-8407201VRA	ACTIVE	CDIP	J	20	1	None	Call TI	Level-NC-NC-NC
5962-8407201VSA	ACTIVE	CFP	W	20	1	None	Call TI	Level-NC-NC-NC
84072012A	ACTIVE	LCCC	FK	20	1	None	Call TI	Level-NC-NC-NC
8407201RA	ACTIVE	CDIP	J	20	1	None	Call TI	Level-NC-NC-NC
8407201SA	ACTIVE	CFP	W	20	1	None	Call TI	Level-NC-NC-NC
JM38510/65403B2A	ACTIVE	LCCC	FK	20	1	None	Call TI	Level-NC-NC-NC
JM38510/65403BRA	ACTIVE	CDIP	J	20	1	None	Call TI	Level-NC-NC-NC
SN54HC373J	ACTIVE	CDIP	J	20	1	None	Call TI	Level-NC-NC-NC
SN74HC373DBLE	OBSOLETE	SSOP	DB	20		None	Call TI	Call TI
SN74HC373DBR	ACTIVE	SSOP	DB	20	2000	Pb-Free (RoHS)	CU NIPDAU	Level-2-260C-1 YEAR/ Level-1-235C-UNLIM
SN74HC373DW	ACTIVE	SOIC	DW	20	25	Pb-Free (RoHS)	CU NIPDAU	Level-2-250C-1 YEAR/ Level-1-235C-UNLIM
SN74HC373DWR	ACTIVE	SOIC	DW	20	2000	Pb-Free (RoHS)	CU NIPDAU	Level-2-250C-1 YEAR/ Level-1-235C-UNLIM
SN74HC373N	ACTIVE	PDIP	N	20	20	Pb-Free (RoHS)	CU NIPDAU	Level-NC-NC-NC
SN74HC373N3	OBSOLETE	PDIP	N	20		None	Call TI	Call TI
SN74HC373NSR	ACTIVE	SO	NS	20	2000	Pb-Free (RoHS)	CU NIPDAU	Level-2-260C-1 YEAR/ Level-1-235C-UNLIM
SN74HC373PW	ACTIVE	TSSOP	PW	20	70	Pb-Free (RoHS)	CU NIPDAU	Level-1-250C-UNLIM
SN74HC373PWLE	OBSOLETE	TSSOP	PW	20		None	Call TI	Call TI
SN74HC373PWR	ACTIVE	TSSOP	PW	20	2000	Pb-Free (RoHS)	CU NIPDAU	Level-1-250C-UNLIM
SN74HC373PWT	ACTIVE	TSSOP	PW	20	250	Pb-Free (RoHS)	CU NIPDAU	Level-1-250C-UNLIM
SNJ54HC373FK	ACTIVE	LCCC	FK	20	1	None	Call TI	Level-NC-NC-NC
SNJ54HC373J	ACTIVE	CDIP	J	20	1	None	Call TI	Level-NC-NC-NC
SNJ54HC373W	ACTIVE	CFP	W	20	1	None	Call TI	Level-NC-NC-NC

⁽¹⁾ The marketing status values are defined as follows:

ACTIVE: Product device recommended for new designs.

LIFEBUY: TI has announced that the device will be discontinued, and a lifetime-buy period is in effect.

NRND: Not recommended for new designs. Device is in production to support existing customers, but TI does not recommend using this part in a new design.

PREVIEW: Device has been announced but is not in production. Samples may or may not be available.

OBSOLETE: TI has discontinued the production of the device.

None: Not yet available Lead (Pb-Free).

Pb-Free (RoHS): TI's terms "Lead-Free" or "Pb-Free" mean semiconductor products that are compatible with the current RoHS requirements for all 6 substances, including the requirement that lead not exceed 0.1% by weight in homogeneous materials. Where designed to be soldered at high temperatures, TI Pb-Free products are suitable for use in specified lead-free processes.

Green (RoHS & no Sb/Br): TI defines "Green" to mean "Pb-Free" and in addition, uses package materials that do not contain halogens, including bromine (Br) or antimony (Sb) above 0.1% of total product weight.

⁽²⁾ Eco Plan - May not be currently available - please check http://www.ti.com/productcontent for the latest availability information and additional product content details.

⁽³⁾ MSL, Peak Temp. -- The Moisture Sensitivity Level rating according to the JEDECindustry standard classifications, and peak solder temperature.



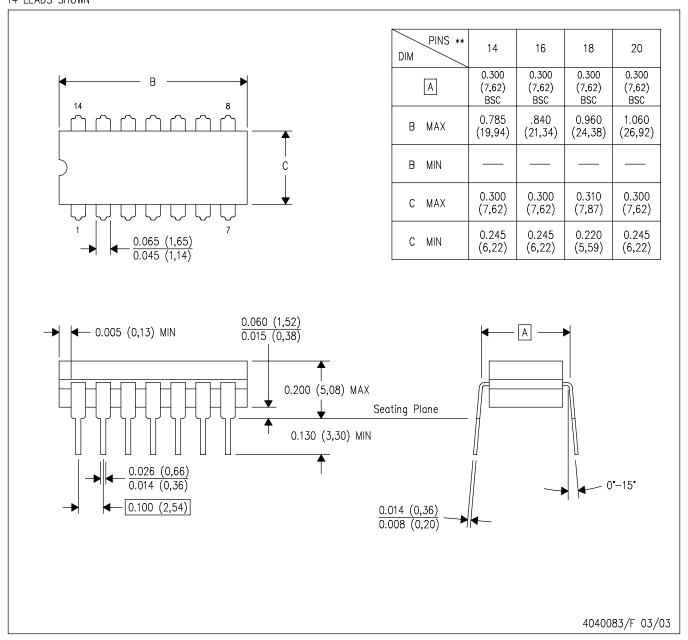
PACKAGE OPTION ADDENDUM

28-Feb-2005

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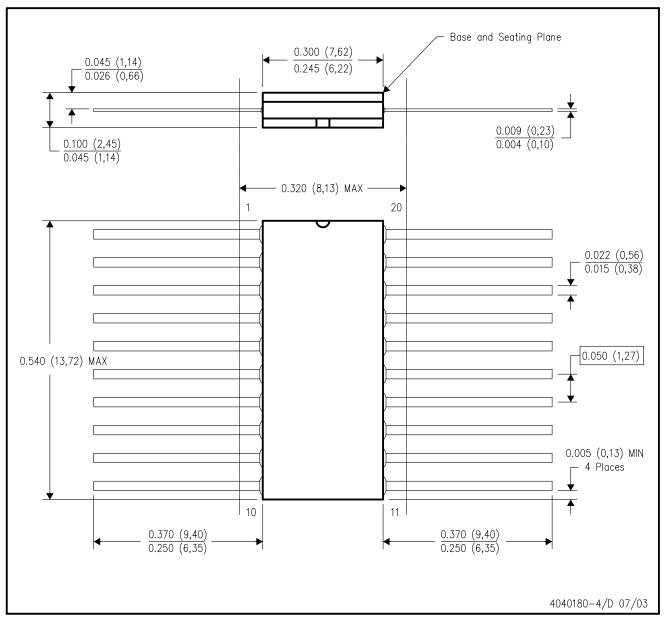
14 LEADS SHOWN



- A. All linear dimensions are in inches (millimeters).
- B. This drawing is subject to change without notice.
- C. This package is hermetically sealed with a ceramic lid using glass frit.
- D. Index point is provided on cap for terminal identification only on press ceramic glass frit seal only.
- E. Falls within MIL STD 1835 GDIP1-T14, GDIP1-T16, GDIP1-T18 and GDIP1-T20.

W (R-GDFP-F20)

CERAMIC DUAL FLATPACK



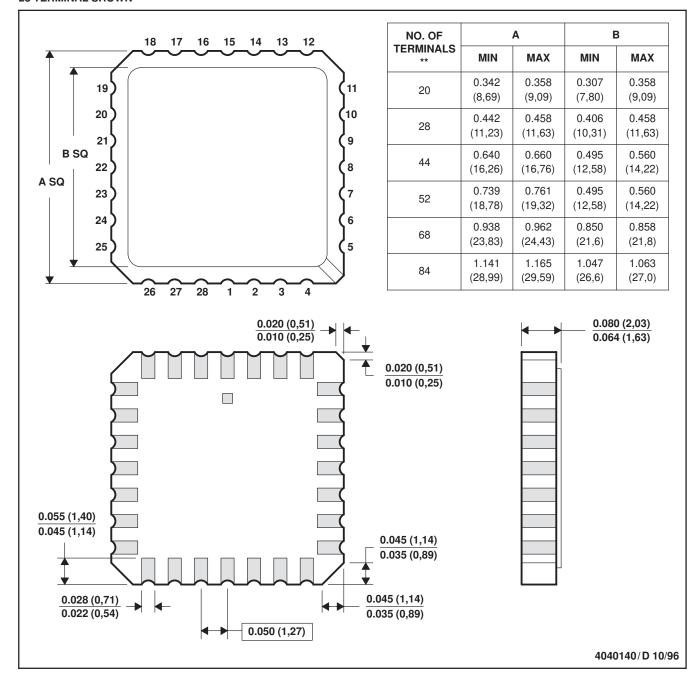
- A. All linear dimensions are in inches (millimeters).
- B. This drawing is subject to change without notice.
- C. This package can be hermetically sealed with a ceramic lid using glass frit.
- D. Index point is provided on cap for terminal identification only.
- E. Falls within Mil-Std 1835 GDFP2-F20



FK (S-CQCC-N**)

28 TERMINAL SHOWN

LEADLESS CERAMIC CHIP CARRIER



NOTES: A. All linear dimensions are in inches (millimeters).

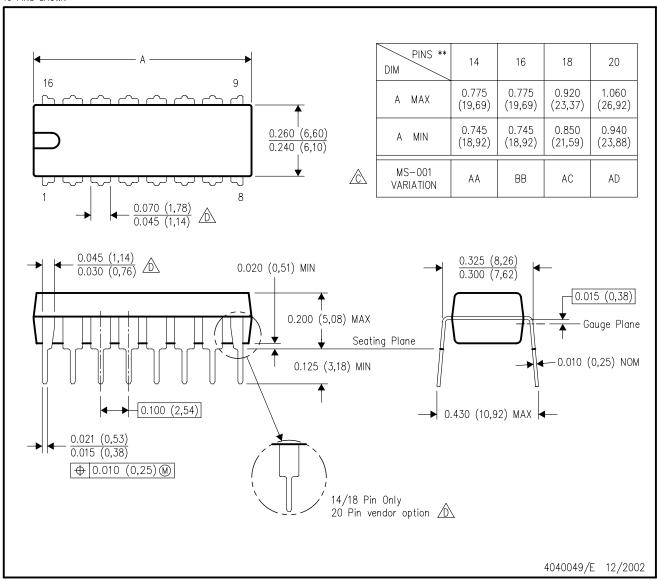
- B. This drawing is subject to change without notice.
- C. This package can be hermetically sealed with a metal lid.
- D. The terminals are gold plated.
- E. Falls within JEDEC MS-004



N (R-PDIP-T**)

PLASTIC DUAL-IN-LINE PACKAGE

16 PINS SHOWN

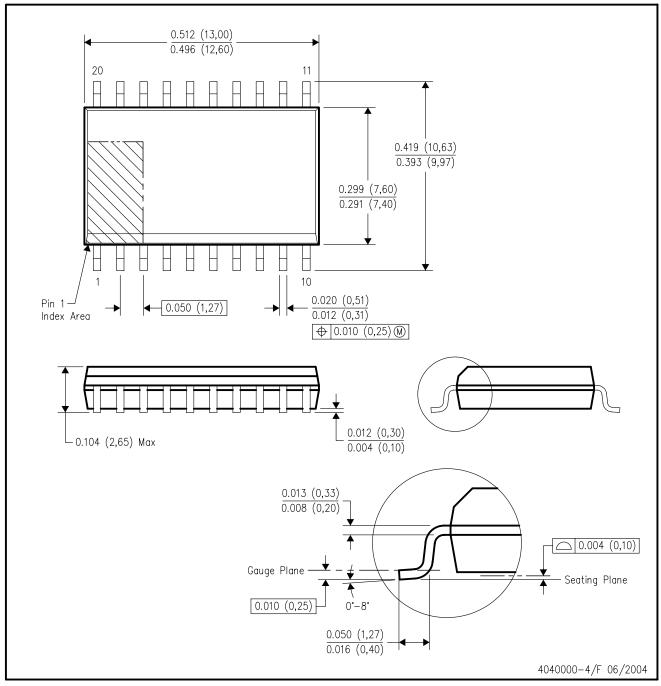


- A. All linear dimensions are in inches (millimeters).
- B. This drawing is subject to change without notice.
- Falls within JEDEC MS-001, except 18 and 20 pin minimum body length (Dim A).
- The 20 pin end lead shoulder width is a vendor option, either half or full width.



DW (R-PDSO-G20)

PLASTIC SMALL-OUTLINE PACKAGE



- A. All linear dimensions are in inches (millimeters).
- B. This drawing is subject to change without notice.
- C. Body dimensions do not include mold flash or protrusion not to exceed 0.006 (0,15).
- D. Falls within JEDEC MS-013 variation AC.

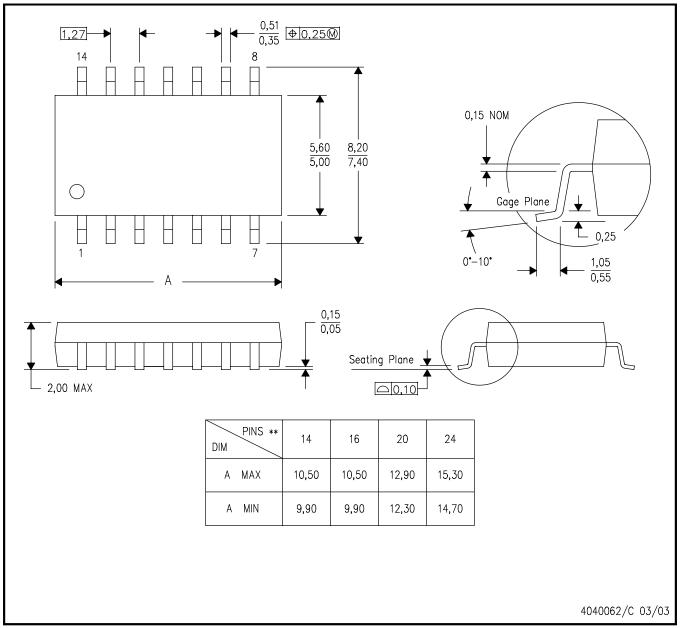


MECHANICAL DATA

NS (R-PDSO-G**)

14-PINS SHOWN

PLASTIC SMALL-OUTLINE PACKAGE



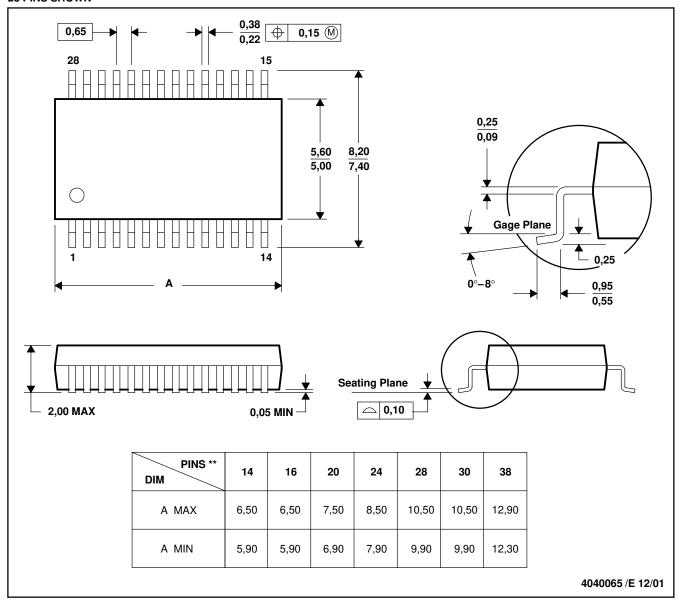
- A. All linear dimensions are in millimeters.
- B. This drawing is subject to change without notice.
- C. Body dimensions do not include mold flash or protrusion, not to exceed 0,15.



DB (R-PDSO-G**)

PLASTIC SMALL-OUTLINE

28 PINS SHOWN



NOTES: A. All linear dimensions are in millimeters.

B. This drawing is subject to change without notice.

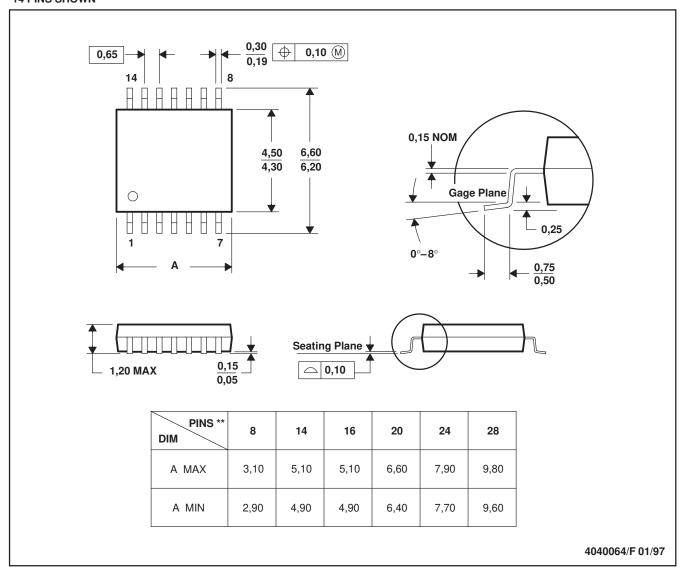
C. Body dimensions do not include mold flash or protrusion not to exceed 0,15.

D. Falls within JEDEC MO-150

PW (R-PDSO-G**)

14 PINS SHOWN

PLASTIC SMALL-OUTLINE PACKAGE



NOTES: A. All linear dimensions are in millimeters.

B. This drawing is subject to change without notice.

C. Body dimensions do not include mold flash or protrusion not to exceed 0,15.

D. Falls within JEDEC MO-153

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